ECEN689: Special Topics in High-Speed Links Circuits and Systems Spring 2011

Lecture 8: Termination & TX Driver Circuits



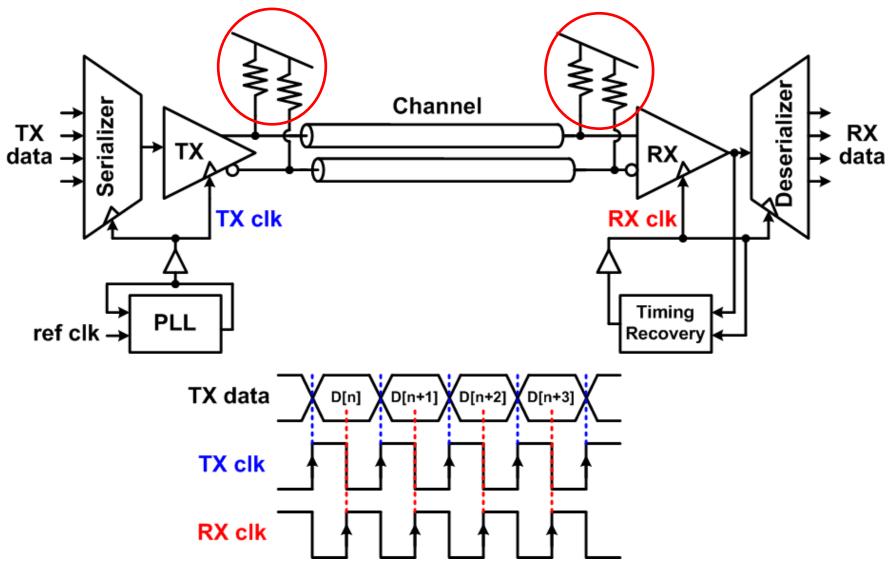
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Announcements & Agenda

- Reading
 - Will post some papers on voltage-mode drivers
- Termination Circuits

TX Driver Circuits

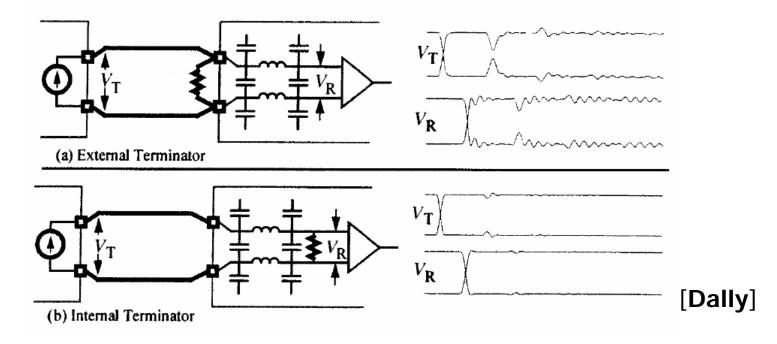
High-Speed Electrical Link System



Termination

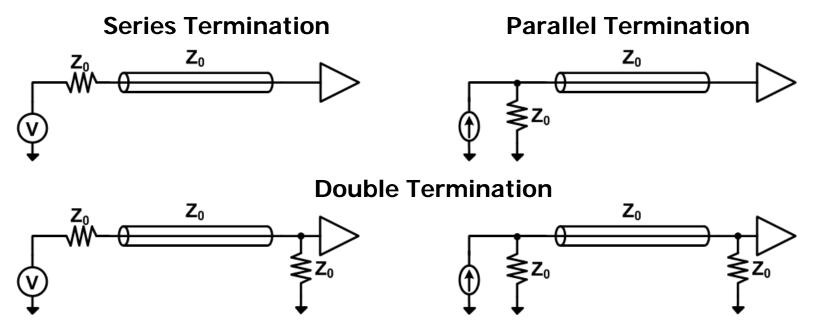
- Off-chip vs on-chip
- Series vs parallel
- DC vs AC Coupling
- Termination circuits

Off-Chip vs On-Chip Termination



- Package parasitics act as an unterminated stub which sends reflections back onto the line
- On-chip termination makes package inductance part of transmission line

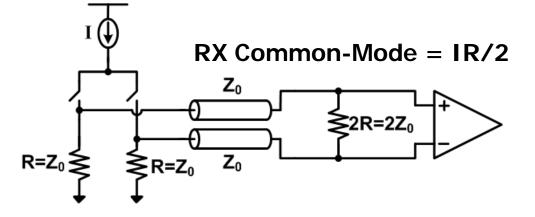
Series vs Parallel Termination



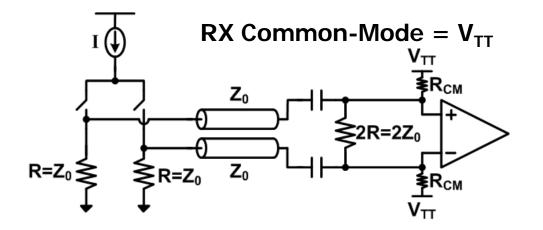
- Low impedance voltage-mode driver typically employs series termination
- High impedance current-mode driver typically employs parallel termination
- Double termination yields best signal quality
 - Done in majority of high performance serial links

AC vs DC Coupled Termination

- DC coupling allows for uncoded data
- RX common-mode set by transmitter signal level



- AC coupling allows for independent RX common-mode level
- Now channel has low frequency cut-off
 - Data must be coded



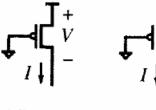
Passive Termination

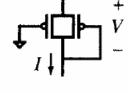
- Choice of integrated resistors involves trade-offs in manufacturing steps, sheet resistance, parasitic capacitance, linearity, and ESD tolerance
- Integrated passive termination resistors are typically realized with unsalicided poly, diffusion, or n-well resistors
- Poly resistors are typically used due to linearity and tighter tolerances, but they typically vary +/-30% over process and temperature

Resistor	Poly	N-diffusion	N-well
Sheet R (Ω/sq)	90±10	300±50	450±200
VC1(V ⁻¹)	0	10 ⁻³	8x10 ⁻³
Parasitic Cap	2-3fF/um ² (min L poly)	0.9fF/um ² (area), 0.04fF/um (perimeter)	0.2fF/um ² (area), 0.7fF/um (perimeter)

Resistor Options (90nm CMOS)

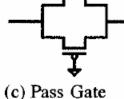
Active Termination





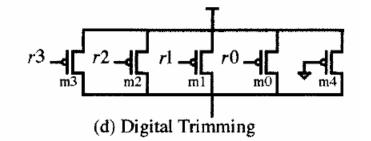


(b) Two-Element

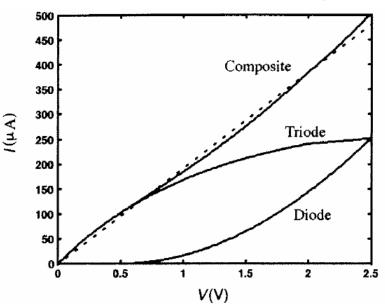




- Transistors must be used for termination in CMOS processes which don't provide resistors
- Triode-biased FET works well for low-swing (<500mV)
 - Adding a diode connected FET increases linear range
- Pass-gate structure allows for differential termination



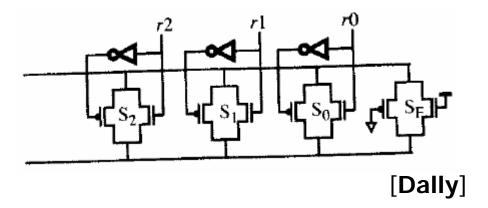




Adjustable Termination

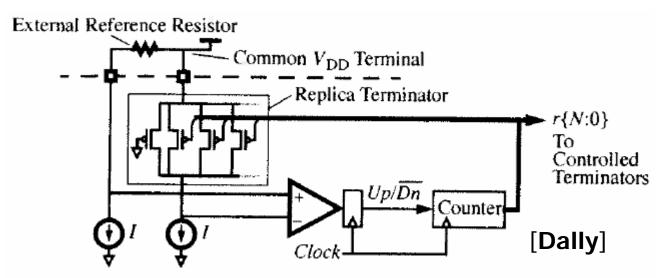
 FET resistance is a function of gate overdrive

$$R_{FET} = \frac{1}{\mu C_{ox} (W/L) (V_{GS} - V_t)}$$



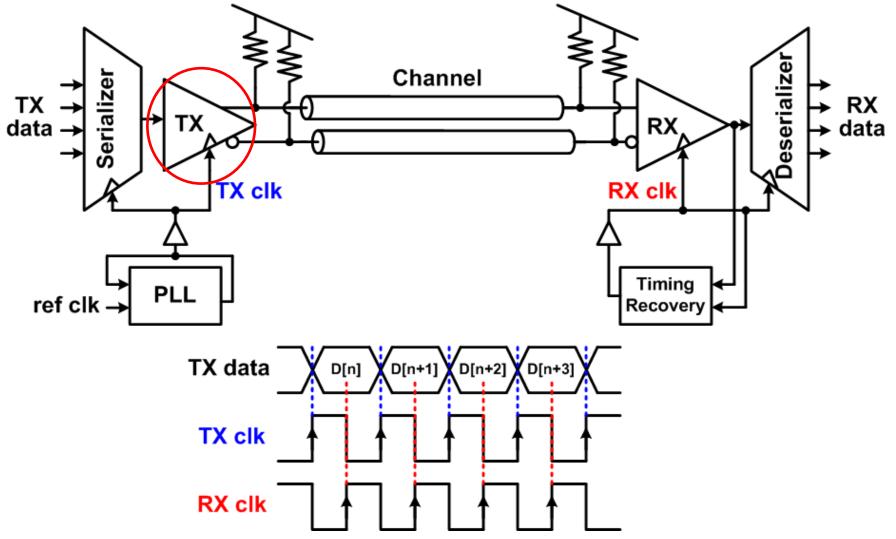
- Large variance in FET threshold voltage requires adjustable termination structures
- Calibration can be done with an analog control voltage or through digital "trimming"
 - Analog control reduces V_{GS} and linear range
 - Digital control is generally preferred

Termination Digital Control Loop



- Off-chip precision resistor is used as reference
- On-chip termination is varied until voltages are within an LSB
 - Dither filter typically used to avoid voltage noise
- Control loop may be shared among several links, but with increased nanometer CMOS variation per-channel calibration may be necessary

High-Speed Electrical Link System



TX Driver Circuits

Single-ended vs differential signaling

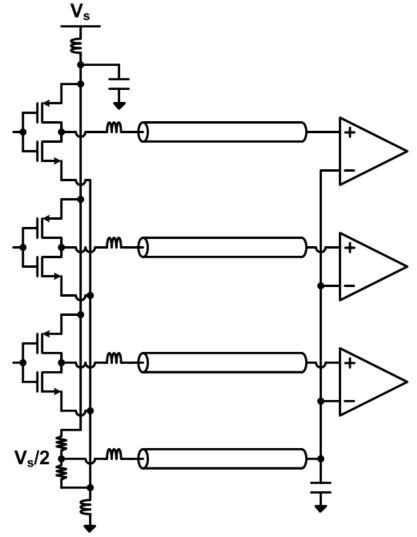
• Current-mode drivers

Voltage-mode drivers

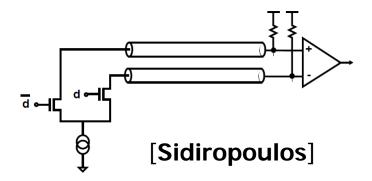
Slew-rate control

Single-Ended Signaling

- Finite supply impedance causes significant
 Simultaneous Switching
 Output (SSO) noise
 (xtalk)
- Necessitates large amounts of decoupling capacitance for supplies and reference voltage
 - Decap limits I/O area more that circuitry



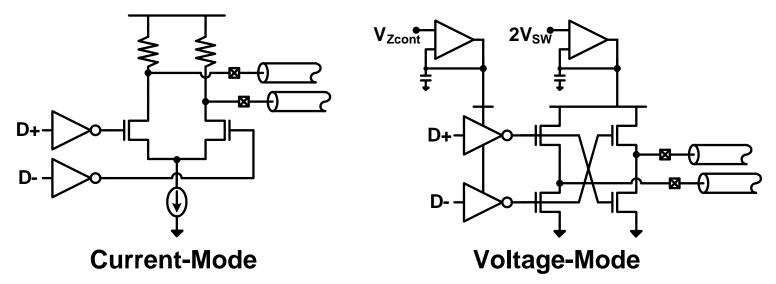
Differential Signaling



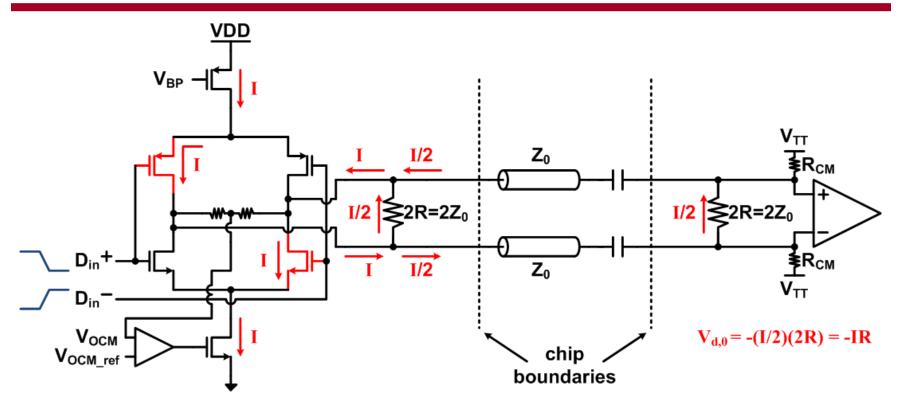
- A difference between voltage or current is sent between two lines
- Requires 2x signal lines relative to single-ended signaling, but less return pins
- Advantages
 - Signal is self-referenced
 - Can achieve twice the signal swing
 - Rejects common-mode noise
 - Return current is ideally only DC

Current vs Voltage-Mode Driver

- Signal integrity considerations (min. reflections) requires 50Ω driver output impedance
- To produce an output drive voltage
 - Current-mode drivers use Norton-equivalent parallel termination
 - Easier to control output impedance
 - Voltage-mode drivers use Thevenin-equivalent series termination
 - Potentially 1/2 to 1/4 the current for a given output swing

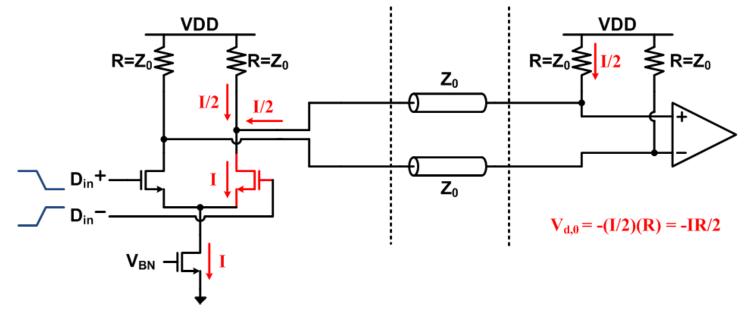


Push-Pull Current-Mode Driver



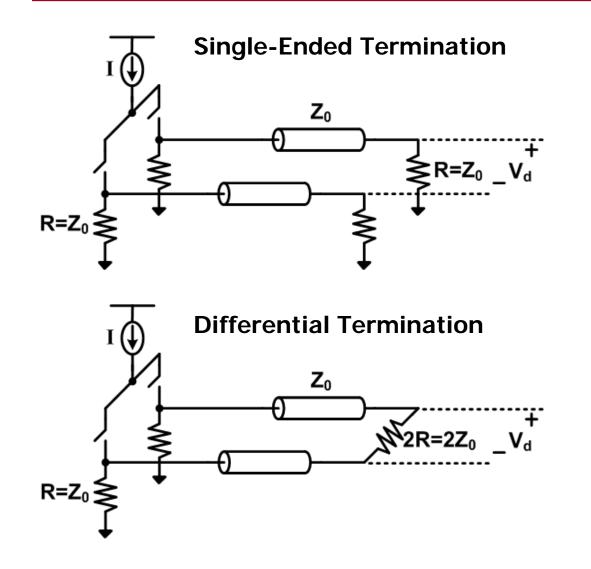
- Used in Low-Voltage Differential Signals (LVDS) standard
- Driver current is ideally constant, resulting in low dI/dt noise
- Dual current sources allow for good PSRR, but headroom can be a problem in low-voltage technologies
- Differential peak-to-peak RX swing is ±IR with double termination

Current-Mode Logic (CML) Driver



- Used in most high performance serial links
- Low voltage operation relative to push-pull driver
 - High output common-mode keeps current source saturated
- Can use DC or AC coupling
 - AC coupling requires data coding
- Differential pp RX swing is ±IR/2 with double termination

Current-Mode Current Levels

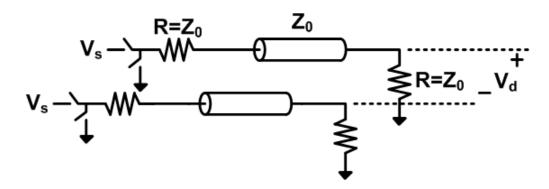


 $V_{d,1} = (I/2)R$ $V_{d,0} = -(I/2)R$ $V_{d,pp} = IR$ $I = rac{V_{d,pp}}{R}$

 $V_{d,1} = (I/4)(2R)$ $V_{d,0} = -(I/4)(2R)$ $V_{d,pp} = IR$ $I = \frac{V_{d,pp}}{R}$

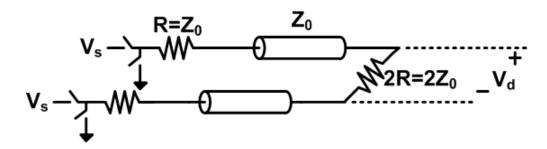
Voltage-Mode Current Levels

Single-Ended Termination



 $V_{d,1} = (V_s/2)$ $V_{d,1} = -(V_s/2)$ $V_{d,pp} = V_s$ $I = (V_s/2R)$ $I = \frac{V_{d,pp}}{V_{d,pp}}$ 2R

Differential Termination



 $V_{d1} = (V_s/2)$ $V_{d1} = -(V_s/2)$ $V_{d,pp} = V_s$ $I = (V_s/4R)$ $I = \frac{V_{d,pp}}{V_{d,pp}}$

Current-Mode vs Voltage-Mode Summary

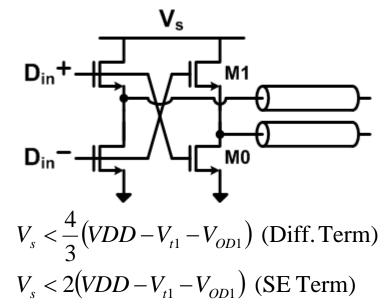
Driver/Termination	Current Level	Normalized Current Level
Current-Mode/SE	$V_{d,pp}/Z_0$	1x
Current-Mode/Diff	$V_{d,pp}/Z_0$	1x
Voltage-Mode/SE	$V_{d,pp}/2Z_0$	0.5x
Voltage-Mode/Diff	$V_{d,pp}/4Z_0$	0.25x

- An ideal voltage-mode driver with differential RX termination enables a *potential* 4x reduction in driver power
- Actual driver power levels also depend on
 - Output impedance control
 - Pre-driver power
 - Equalization implementation

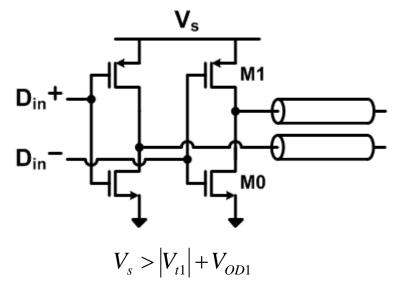
Voltage-Mode Drivers

- Voltage-mode driver implementation depends on output swing requirements
- For low-swing (<400-500mVpp), an all NMOS driver is suitable
- For high-swing, CMOS driver is used

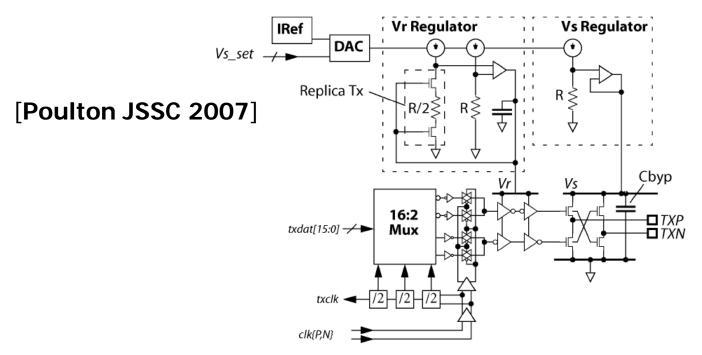
Low-Swing Voltage-Mode Driver



High-Swing Voltage-Mode Driver

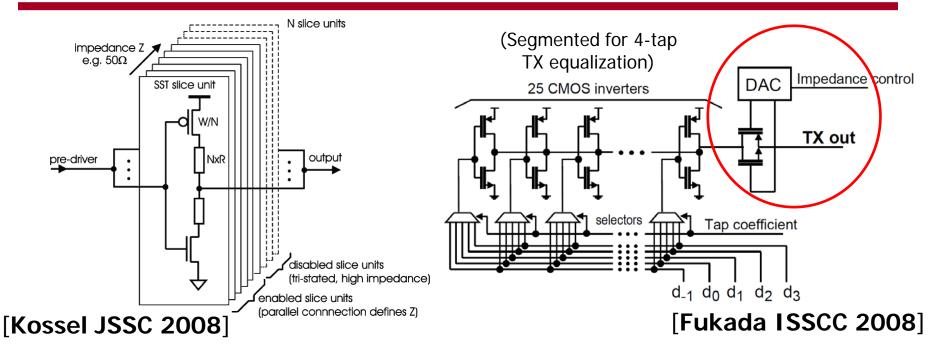


Low-Swing VM Driver Impedance Control



- A linear regulator sets the output stage supply, V_s
- Termination is implemented by output NMOS transistors
- To compensate for PVT and varying output swing levels, the pre-drive supply is adjusted with a feedback loop
- The top and bottom output stage transistors need to be sized differently, as they see a different $V_{\rm OD}$

High-Swing VM Driver Impedance Control

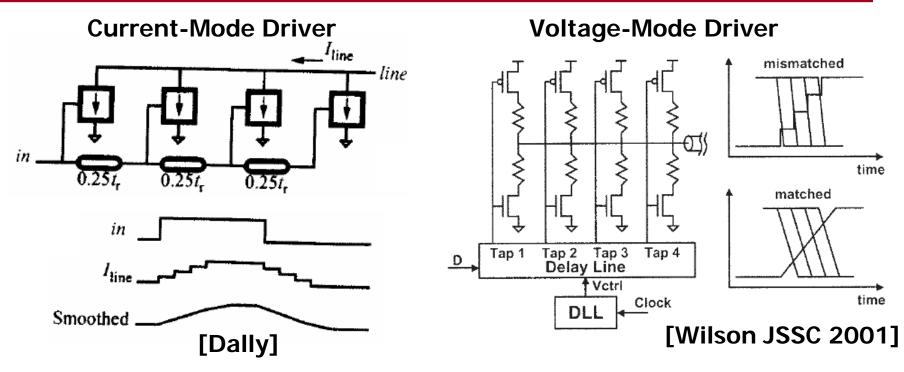


- High-swing voltage-mode driver termination is implemented with a combination of output driver transistors and series resistors
- To meet termination resistance levels (50Ω), large output transistors are required
 - Degrades potential power savings vs current-mode driver

TX Driver Slew Rate Control

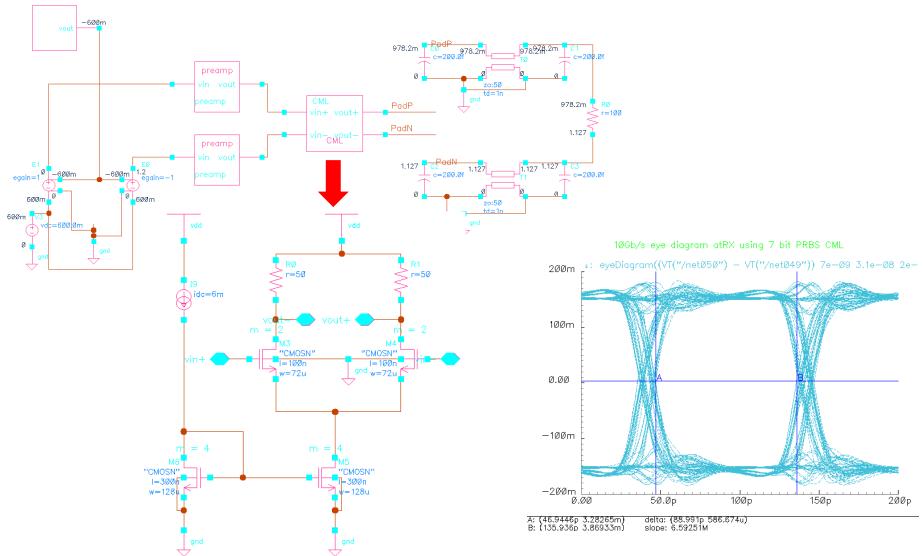
- Output transition times should be controlled
 - Too slow
 - Limits max data rate
 - Too fast
 - Can excite resonant circuits, resulting in ISI due to ringing
 - Cause excessive crosstalk
- Slew rate control reduces reflections and crosstalk

Slew Rate Control w/ Segmented Driver

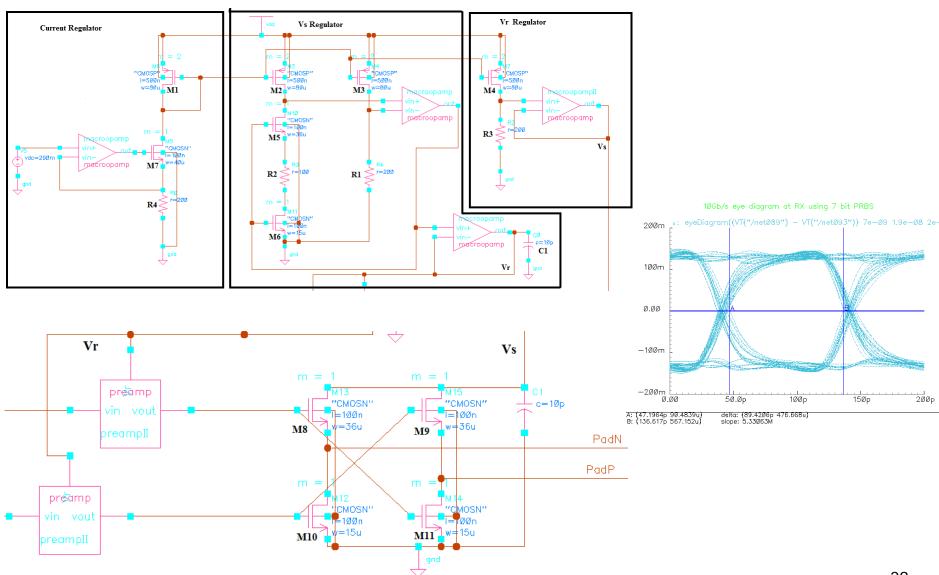


- Slew rate control can be implemented with a segmented output driver
- Segments turn-on time are spaced by 1/n of desired transition time
- Predriver transition time should also be controlled

Current-Mode Driver Example



Voltage-Mode Driver Example



Next Time

- TX circuit speed limitations
 - Clock distribution
 - Multiplexing circuits
- Receiver Circuits